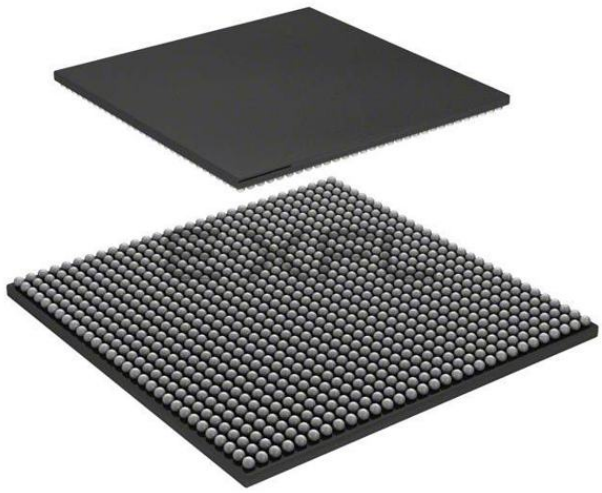
AMD Xilinx - XC3S2000-4FG900I Datasheet



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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	5120
Number of Logic Elements/Cells	46080
Total RAM Bits	737280
Number of I/O	565
Number of Gates	2000000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3s2000-4fg900i

Table 4: **Example Ordering Information**

Device	Speed Grade		Package Type/Number of Pins		Temperature Range (T_j)	
XC3S50	-4	Standard Performance	VQ(G)100	100-pin Very Thin Quad Flat Pack (VQFP)	C	Commercial (0°C to 85°C)
XC3S200	-5	High Performance(1)	CP(G)132(2)	132-pin Chip-Scale Package (CSP)	I	Industrial (–40°C to 100°C)
XC3S400			TQ(G)144	144-pin Thin Quad Flat Pack (TQFP)		
XC3S1000			PQ(G)208	208-pin Plastic Quad Flat Pack (PQFP)		
XC3S1500			FT(G)256	256-ball Fine-Pitch Thin Ball Grid Array (FTBGA)		
XC3S2000			FG(G)320	320-ball Fine-Pitch Ball Grid Array (FBGA)		
XC3S4000			FG(G)456	456-ball Fine-Pitch Ball Grid Array (FBGA)		
XC3S5000			FG(G)676	676-ball Fine-Pitch Ball Grid Array (FBGA)		
			FG(G)900	900-ball Fine-Pitch Ball Grid Array (FBGA)		
			FG(G)1156(2)	1156-ball Fine-Pitch Ball Grid Array (FBGA)		

Notes:

1. The -5 speed grade is exclusively available in the Commercial temperature range.
2. The CP132, CPG132, FG1156, and FGG1156 packages are discontinued. See http://www.xilinx.com/support/documentation/spartan-3_customer_notices.htm.

Revision History

Date	Version	Description
04/11/03	1.0	Initial Xilinx release.
04/24/03	1.1	Updated block RAM, DCM, and multiplier counts for the XC3S50.
12/24/03	1.2	Added the FG320 package.
07/13/04	1.3	Added information on Pb-free packaging options.
01/17/05	1.4	Referenced Spartan-3 XA Automotive FPGA families in Table 1. Added XC3S50CP132, XC3S2000FG456, XC3S4000FG676 options to Table 3. Updated Package Marking to show mask revision code, fabrication facility code, and process technology code.
08/19/05	1.5	Added package markings for BGA packages (Figure 3) and CP132/CPG132 packages (Figure 4). Added differential (complementary single-ended) HSTL and SSTL I/O standards.
04/03/06	2.0	Increased number of supported single-ended and differential I/O standards.
04/26/06	2.1	Updated document links.
05/25/07	2.2	Updated Package Marking to allow for dual-marking.
11/30/07	2.3	Added XC3S5000 FG(G)676 to Table 3. Noted that FG(G)1156 package is being discontinued and updated max I/O count.
06/25/08	2.4	Updated max I/O counts based on FG1156 discontinuation. Clarified dual mark in Package Marking. Updated formatting and links.
12/04/09	2.5	CP132 and CPG132 packages are being discontinued. Added link to Spartan-3 FPGA customer notices. Updated Table 3 with package footprint dimensions.
10/29/12	3.0	Added Notice of Disclaimer section. Per XCN07022, updated the discontinued FG1156 and FGG1156 package discussion throughout document. Per XCN08011, updated the discontinued CP132 and CPG132 package discussion throughout document. Although the package is discontinued, updated the marking on Figure 4. This product is not recommended for new designs.

Table 8: **Single-Ended I/O Standards**

Signal Standard (IOSTANDARD)	V_{CCO} (Volts)		V_{REF} for Inputs (Volts)(1)	Board Termination Voltage (V_{TT}) in Volts
	For Outputs	For Inputs		
GTL	Note 2	Note 2	0.8	1.2
GTLP	Note 2	Note 2	1	1.5
HSTL_I	1.5	–	0.75	0.75
HSTL_III	1.5	–	0.9	1.5
HSTL_I_18	1.8	–	0.9	0.9
HSTL_II_18	1.8	–	0.9	0.9
HSTL_III_18	1.8	–	1.1	1.8
LVCMOS12	1.2	1.2	–	–
LVCMOS15	1.5	1.5	–	–
LVCMOS18	1.8	1.8	–	–
LVCMOS25	2.5	2.5	–	–
LVCMOS33	3.3	3.3	–	–
LVTTL	3.3	3.3	–	–
PCI33_3	3.0	3.0	–	–
SSTL18_I	1.8	–	0.9	0.9
SSTL18_II	1.8	–	0.9	0.9
SSTL2_I	2.5	–	1.25	1.25
SSTL2_II	2.5	–	1.25	1.25

Notes:

1. Banks 4 and 5 of any Spartan-3 device in a VQ100 package do not support signal standards using V_{REF}.
2. The V_{CCO} level used for the GTL and GTLP standards must be no lower than the termination voltage (V_{TT}), nor can it be lower than the voltage at the I/O pad.
3. See Table 10 for a listing of the single-ended DCI standards.

Differential standards employ a pair of signals, one the opposite polarity of the other. The noise canceling (e.g., Common-Mode Rejection) properties of these standards permit exceptionally high data transfer rates. This section introduces the differential signaling capabilities of Spartan-3 devices.

Each device-package combination designates specific I/O pairs that are specially optimized to support differential standards. A unique “L-number”, part of the pin name, identifies the line-pairs associated with each bank (see Figure 40, page 112). For each pair, the letters ‘P’ and ‘N’ designate the true and inverted lines, respectively. For example, the pin names IO_L43P_7 and IO_L43N_7 indicate the true and inverted lines comprising the line pair L43 on Bank 7. The V_{CCO} lines provide current to the outputs. The V_{CCAUX} lines supply power to the differential inputs, making them independent of the V_{CCO} voltage for an I/O bank. The V_{REF} lines are not used. Select the V_{CCO} level to suit the desired differential standard according to Table 9.

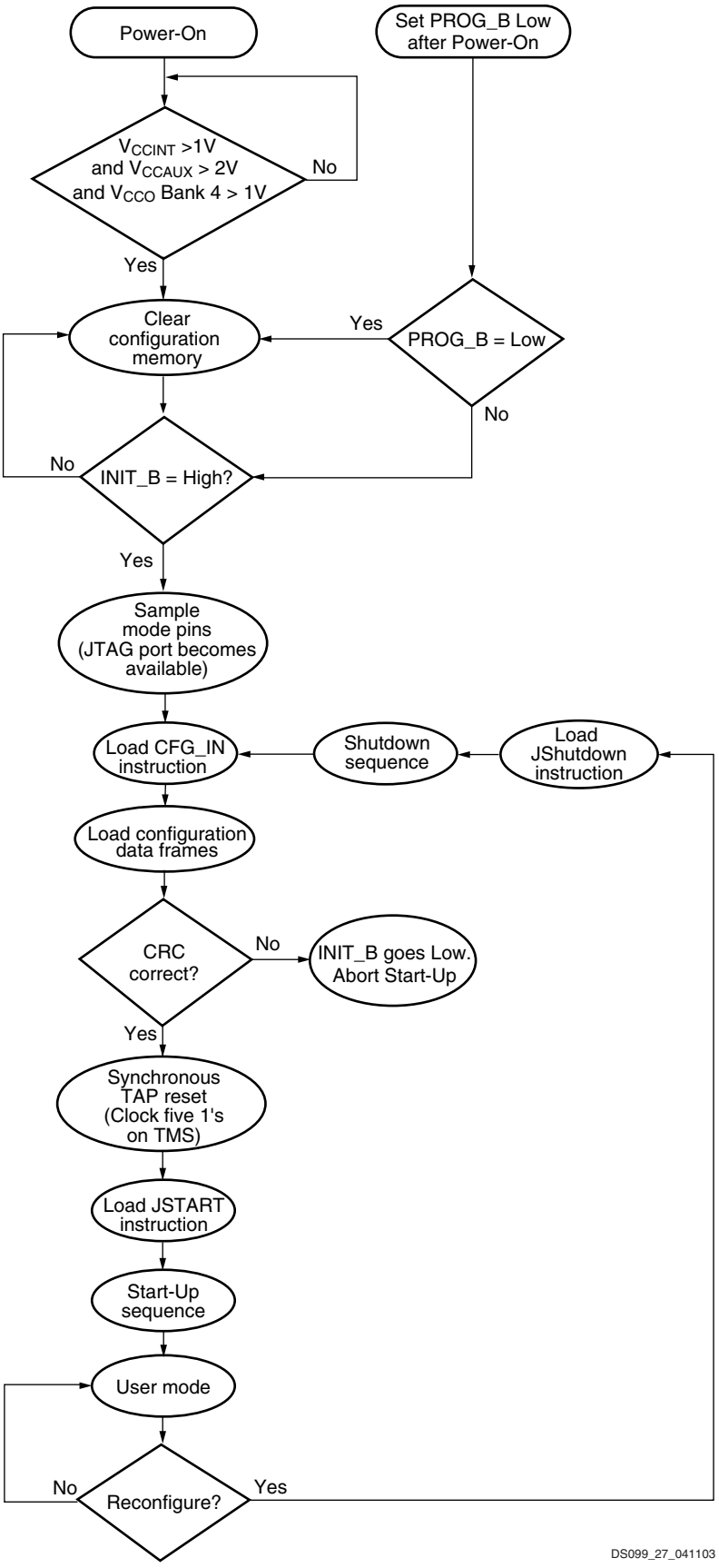

Figure 30: **Boundary-Scan Configuration Flow Diagram**

Switching Characteristics

All Spartan-3 devices are available in two speed grades: –4 and the higher performance –5. Switching characteristics in this document may be designated as Advance, Preliminary, or Production. Each category is defined as follows:

Advance: These specifications are based on simulations only and are typically available soon after establishing FPGA specifications. Although speed grades with this designation are considered relatively stable and conservative, some under-reported delays may still occur.

Preliminary: These specifications are based on complete early silicon characterization. Devices and speed grades with this designation are intended to give a better indication of the expected performance of production silicon. The probability of under-reporting preliminary delays is greatly reduced compared to Advance data.

Production: These specifications are approved once enough production silicon of a particular device family member has been characterized to provide full correlation between speed files and devices over numerous production lots. There is no under-reporting of delays, and customers receive formal notification of any subsequent changes. Typically, the slowest speed grades transition to Production before faster speed grades.

Production-quality systems must use FPGA designs compiled using a Production status speed file. FPGAs designs using a less mature speed file designation may only be used during system prototyping or preproduction qualification. FPGA designs using Advance or Preliminary status speed files should never be used in a production-quality system.

Whenever a speed file designation changes, as a device matures toward Production status, rerun the Xilinx ISE software on the FPGA design to ensure that the FPGA design incorporates the latest timing information and software updates.

Xilinx ISE Software Updates: http://www.xilinx.com/support/download/index.htm

All specified limits are representative of worst-case supply voltage and junction temperature conditions. Unless otherwise noted, the following applies: Parameter values apply to all Spartan-3 devices. All parameters representing voltages are measured with respect to GND.

Selected timing parameters and their representative values are included below either because they are important as general design requirements or they indicate fundamental device performance characteristics. The Spartan-3 FPGA v1.38 speed files are the original source for many but not all of the values. The v1.38 speed files are available in Xilinx Integrated Software Environment (ISE) software version 8.2i.

The speed grade designations for these files are shown in Table 39. For more complete, more precise, and worst-case data, use the values reported by the Xilinx static timing analyzer (TRACE in the Xilinx development software) and back-annotated to the simulation netlist.

Table 39: **Spartan-3 FPGA Speed Grade Designations (ISE v8.2i or Later)**

Device	Advance	Preliminary	Production
XC3S50			-4, -5 (v1.37 and later)
XC3S200			
XC3S400			
XC3S1000			
XC3S1500			
XC3S2000			
XC3S4000			
XC3S5000			-4, -5 (v1.38 and later)

Date	Version	Description
05/25/07	2.2	Improved absolute maximum voltage specifications in Table 28, providing additional overshoot allowance. Improved XC3S50 HBM ESD to 2000V in Table 28. Based on extensive 90 nm production data, improved (reduced) the maximum quiescent current limits for the I_{CCINTQ} and I_{CCOQ} specifications in Table 34. Widened the recommended voltage range for the PCI standard and clarified the hysteresis footnote in Table 35. Noted restriction on combining differential outputs in Table 38. Updated footnote 1 in Table 64.
11/30/07	2.3	Updated 3.3V VCCO max from 3.45V to 3.465V in Table 32 and elsewhere. Reduced t_{ICCK} minimum from 0.50µs to 0.25µs in Table 65. Updated links to technical documentation.
06/25/08	2.4	Clarified dual marking. Added Mask and Fab Revisions. Added references to XAPP459 in Table 28 and Table 32. Removed absolute minimum and added footnote referring to timing analyzer for minimum delay values. Added HSLVDCI to Table 48 and Table 50. Updated t_{DICK} in Table 51 to match largest possible value in speed file. Updated formatting and links.
12/04/09	2.5	Updated notes 2 and 3 in Table 28. Removed silicon process specific information and revised notes in Table 30. Updated note 3 in Table 32. Updated note 3 in Table 34. Updated note 5 in Table 35. Updated V_{OL} max and V_{OH} min for SSTL2_II in Table 36. Updated note 5 in Table 36. Updated JTAG Waveforms in Figure 39. Updated V_{ICM} max for LVPECL_25 in Table 37. Updated RT and VT for LVDS_25_DCI in Table 48. Updated Simultaneously Switching Output Guidelines. Noted that the CP132 package is being discontinued in Table 49. Removed minimum values for T_{MULTCK} clock-to-output times in Table 54. Updated footnote 3 in Table 58. Removed minimum values for T_{MULT} propagation times in Table 55. Removed silicon process specific information and revised notes in Table 61. Updated Phase Shifter (PS).
10/29/12	3.0	Added Notice of Disclaimer. Per XCN07022, updated the discontinued FG1156 and FGG1156 package discussion throughout document. Per XCN08011, updated the discontinued CP132 and CPG132 package discussion throughout document. Revised description of V_{IN} in Table 32 and added note 7. Added note 4 to Table 33. This product is not recommended for new designs.

Table 69: **Types of Pins on Spartan-3 FPGAs *(Cont'd)***

Pin Type/ Color Code	Description	Pin Name
VREF	Dual-purpose pin that is either a user-I/O pin or, along with all other VREF pins in the same bank, provides a reference voltage input for certain I/O standards. If used for a reference voltage within a bank, all VREF pins within the bank must be connected.	IO/VREF_# IO_Lxxy_#/VREF_#
GND	Dedicated ground pin. The number of GND pins depends on the package used. All must be connected.	GND
VCCAUX	Dedicated auxiliary power supply pin. The number of VCCAUX pins depends on the package used. All must be connected to +2.5V.	VCCAUX
VCCINT	Dedicated internal core logic power supply pin. The number of VCCINT pins depends on the package used. All must be connected to +1.2V.	VCCINT
VCCO	Dedicated I/O bank, output buffer power supply pin. Along with other VCCO pins in the same bank, this pin supplies power to the output buffers within the I/O bank and sets the input threshold voltage for some I/O standards.	VCCO_# **CP132 and TQ144 Packages Only:** VCCO_LEFT, VCCO_TOP, VCCO_RIGHT, VCCO_BOTTOM
GCLK	Dual-purpose pin that is either a user-I/O pin or an input to a specific global buffer input. Every package has eight dedicated GCLK pins.	IO_Lxxy_#/GCLK0, IO_Lxxy_#/GCLK1, IO_Lxxy_#/GCLK2, IO_Lxxy_#/GCLK3, IO_Lxxy_#/GCLK4, IO_Lxxy_#/GCLK5, IO_Lxxy_#/GCLK6, IO_Lxxy_#/GCLK7
N.C.	This package pin is not connected in this specific device/package combination but may be connected in larger devices in the same package.	N.C.

Notes:

1. # = I/O bank number, an integer between 0 and 7.

I/Os with Lxxy_# are part of a differential output pair. 'L' indicates differential output capability. The "xx" field is a two-digit integer, unique to each bank that identifies a differential pin-pair. The 'y' field is either 'P' for the true signal or 'N' for the inverted signal in the differential pair. The '#' field is the I/O bank number.

Pin Definitions

Table 70 provides a brief description of each pin listed in the Spartan-3 FPGA pinout tables and package footprint diagrams. Pins are categorized by their pin type, as listed in Table 69. See Detailed, Functional Pin Descriptions for more information.

Differential Pair Labeling

A pin supports differential standards if the pin is labeled in the format “Lxxy_#”. The pin name suffix has the following significance. Figure 40 provides a specific example showing a differential input to and a differential output from Bank 2.

- ‘L’ indicates differential capability.
- "xx" is a two-digit integer, unique for each bank, that identifies a differential pin-pair.
- ‘y’ is replaced by ‘P’ for the true signal or ‘N’ for the inverted. These two pins form one differential pin-pair.
- ‘#’ is an integer, 0 through 7, indicating the associated I/O bank.

If unused, these pins are in a high impedance state. The Bitstream generator option UnusedPin enables a pull-up or pull-down resistor on all unused I/O pins.

Behavior from Power-On through End of Configuration

During the configuration process, all pins that are not actively involved in the configuration process are in a high-impedance state. The CONFIG- and JTAG-type pins have an internal pull-up resistor to VCCAUX during configuration. For all other I/O pins, the HSWAP_EN input determines whether or not pull-up resistors are activated during configuration. HSWAP_EN = 0 enables the pull-up resistors. HSWAP_EN = 1 disables the pull-up resistors allowing the pins to float, which is the desired state for hot-swap applications.

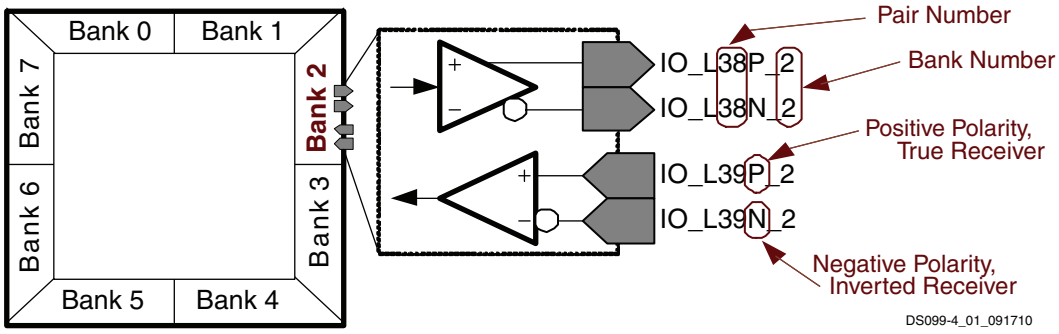

Figure 40: **Differential Pair Labelling**

DUAL Type: Dual-Purpose Configuration and I/O Pins

These pins serve dual purposes. The user-I/O pins are temporarily borrowed during the configuration process to load configuration data into the FPGA. After configuration, these pins are then usually available as a user I/O in the application. If a pin is not applicable to the specific configuration mode—controlled by the mode select pins M2, M1, and M0—then the pin behaves as an I/O-type pin.

There are 12 dual-purpose configuration pins on every package, six of which are part of I/O Bank 4, the other six part of I/O Bank 5. Only a few of the pins in Bank 4 are used in the Serial configuration modes.

See Pin Behavior During Configuration, page 122.

Serial Configuration Modes

This section describes the dual-purpose pins used during either Master or Slave Serial mode. See Table 75 for Mode Select pin settings required for Serial modes. All such pins are in Bank 4 and powered by VCCO_4.

In both the Master and Slave Serial modes, DIN is the serial configuration data input. The D1-D7 inputs are unused in serial mode and behave like general-purpose I/O pins.

In all the cases, the configuration data is synchronized to the rising edge of the CCLK clock signal.

The DIN, DOUT, and INIT_B pins can be retained in the application to support reconfiguration by setting the Persist bitstream generation option. However, the serial modes do not support device readback.

Table 85: **Maximum User I/Os by Package**

Device	Package	Maximum User I/Os	Maximum Differential Pairs	All Possible I/O Pins by Type					N.C.
				I/O	DUAL	DCI	VREF	GCLK	
XC3S50	VQ100	63	29	22	12	14	7	8	0
XC3S200	VQ100	63	29	22	12	14	7	8	0
XC3S50	CP132(1)	89	44	44	12	14	11	8	0
XC3S50	TQ144	97	46	51	12	14	12	8	0
XC3S200	TQ144	97	46	51	12	14	12	8	0
XC3S400	TQ144	97	46	51	12	14	12	8	0
XC3S50	PQ208	124	56	72	12	16	16	8	17
XC3S200	PQ208	141	62	83	12	16	22	8	0
XC3S400	PQ208	141	62	83	12	16	22	8	0
XC3S200	FT256	173	76	113	12	16	24	8	0
XC3S400	FT256	173	76	113	12	16	24	8	0
XC3S1000	FT256	173	76	113	12	16	24	8	0
XC3S400	FG320	221	100	156	12	16	29	8	0
XC3S1000	FG320	221	100	156	12	16	29	8	0
XC3S1500	FG320	221	100	156	12	16	29	8	0
XC3S400	FG456	264	116	196	12	16	32	8	69
XC3S1000	FG456	333	149	261	12	16	36	8	0
XC3S1500	FG456	333	149	261	12	16	36	8	0
XC3S2000	FG456	333	149	261	12	16	36	8	0
XC3S1000	FG676	391	175	315	12	16	40	8	98
XC3S1500	FG676	487	221	403	12	16	48	8	2
XC3S2000	FG676	489	221	405	12	16	48	8	0
XC3S4000	FG676	489	221	405	12	16	48	8	0
XC3S5000	FG676	489	221	405	12	16	48	8	0
XC3S2000	FG900	565	270	481	12	16	48	8	68
XC3S4000	FG900	633	300	549	12	16	48	8	0
XC3S5000	FG900	633	300	549	12	16	48	8	0
XC3S4000	FG1156(1)	712	312	621	12	16	55	8	73
XC3S5000	FG1156(1)	784	344	692	12	16	56	8	1

Notes:

1. The CP132, CPG132, FG1156, and FGG1156 packages are discontinued. See http://www.xilinx.com/support/documentation/spartan-3_customer_notices.htm.

Electronic versions of the package pinout tables and footprints are available for download from the Xilinx website. Using a spreadsheet program, the data can be sorted and reformatted according to any specific needs. Similarly, the ASCII-text file is easily parsed by most scripting programs. Download the files from the following location:

http://www.xilinx.com/support/documentation/data_sheets/s3_pin.zip

TQ144: 144-lead Thin Quad Flat Package

The XC3S50, the XC3S200, and the XC3S400 are available in the 144-lead thin quad flat package, TQ144. All devices share a common footprint for this package as shown in Table 91 and Figure 46.

The TQ144 package only has four separate VCCO inputs, unlike the BGA packages, which have eight separate VCCO inputs. The TQ144 package has a separate VCCO input for the top, bottom, left, and right. However, there are still eight separate I/O banks, as shown in Table 91 and Figure 46. Banks 0 and 1 share the VCCO_TOP input, Banks 2 and 3 share the VCCO_RIGHT input, Banks 4 and 5 share the VCCO_BOTTOM input, and Banks 6 and 7 share the VCCO_LEFT input.

All the package pins appear in Table 91 and are sorted by bank number, then by pin name. Pairs of pins that form a differential I/O pair appear together in the table. The table also shows the pin number for each pin and the pin type, as defined earlier.

An electronic version of this package pinout table and footprint diagram is available for download from the Xilinx website at http://www.xilinx.com/support/documentation/data_ sheets/s3_pin.zip.

Pinout Table

Table 91: **TQ144 Package Pinout**

Bank	XC3S50, XC3S200, XC3S400 Pin Name	TQ144 Pin Number	Type
0	IO_L01N_0/VRP_0	P141	DCI
0	IO_L01P_0/VRN_0	P140	DCI
0	IO_L27N_0	P137	I/O
0	IO_L27P_0	P135	I/O
0	IO_L30N_0	P132	I/O
0	IO_L30P_0	P131	I/O
0	IO_L31N_0	P130	I/O
0	IO_L31P_0/VREF_0	P129	VREF
0	IO_L32N_0/GCLK7	P128	GCLK
0	IO_L32P_0/GCLK6	P127	GCLK
1	IO	P116	I/O
1	IO_L01N_1/VRP_1	P113	DCI
1	IO_L01P_1/VRN_1	P112	DCI
1	IO_L28N_1	P119	I/O
1	IO_L28P_1	P118	I/O
1	IO_L31N_1/VREF_1	P123	VREF
1	IO_L31P_1	P122	I/O
1	IO_L32N_1/GCLK5	P125	GCLK
1	IO_L32P_1/GCLK4	P124	GCLK
2	IO_L01N_2/VRP_2	P108	DCI
2	IO_L01P_2/VRN_2	P107	DCI
2	IO_L20N_2	P105	I/O
2	IO_L20P_2	P104	I/O
2	IO_L21N_2	P103	I/O
2	IO_L21P_2	P102	I/O
2	IO_L22N_2	P100	I/O
2	IO_L22P_2	P99	I/O

PQ208 Footprint

Left Half of Package (Top View)

XC3S50
(124 max. user I/O)

72 **I/O:** Unrestricted, general-purpose user I/O

16 **VREF:** User I/O or input voltage reference for bank

17 **N.C.:** Unconnected pins for XC3S50 (◆)

XC3S200, XC3S400
(141 max user I/O)

83 **I/O:** Unrestricted, general-purpose user I/O

22 **VREF:** User I/O or input voltage reference for bank

0 **N.C.:** No unconnected pins in this package

All devices

12 **DUAL:** Configuration pin, then possible user I/O

8 **GCLK:** User I/O or global clock buffer input

16 **DCI:** User I/O or reference resistor input for bank

7 **CONFIG:** Dedicated configuration pins

4 **JTAG:** Dedicated JTAG port pins

4 **VCCINT:** Internal core voltage supply (+1.2V)

12 **VCCO:** Output voltage supply for bank

8 **VCCAUX:** Auxiliary voltage supply (+2.5V)

28 **GND:** Ground

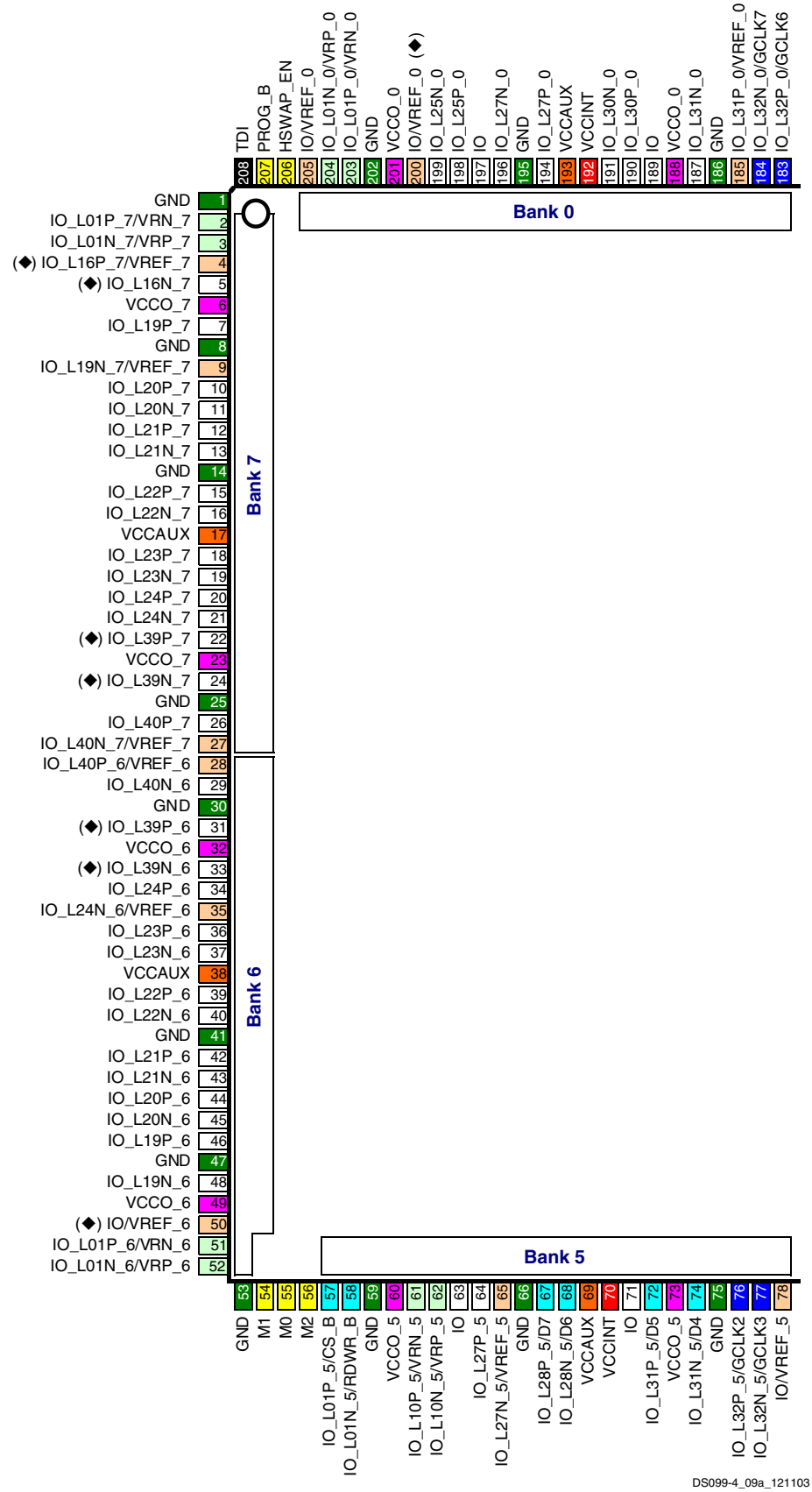

Figure 47: **PQ208 Package Footprint (Top View). Note pin 1 indicator in top-left corner and logo orientation.**

Table 96: **FT256 Package Pinout *(Cont'd)***

Bank	XC3S200, XC3S400, XC3S1000 Pin Name	FT256 Pin Number	Type
4	IO_L28N_4	P11	I/O
4	IO_L28P_4	R11	I/O
4	IO_L29N_4	M10	I/O
4	IO_L29P_4	N10	I/O
4	IO_L30N_4/D2	P10	DUAL
4	IO_L30P_4/D3	R10	DUAL
4	IO_L31N_4/INIT_B	N9	DUAL
4	IO_L31P_4/DOUT/BUSY	P9	DUAL
4	IO_L32N_4/GCLK1	R9	GCLK
4	IO_L32P_4/GCLK0	T9	GCLK
4	VCCO_4	L9	VCCO
4	VCCO_4	L10	VCCO
4	VCCO_4	M9	VCCO
5	IO	N5	I/O
5	IO	P7	I/O
5	IO	T5	I/O
5	IO/VREF_5	T8	VREF
5	IO_L01N_5/RDWR_B	T3	DUAL
5	IO_L01P_5/CS_B	R3	DUAL
5	IO_L10N_5/VRP_5	T4	DCI
5	IO_L10P_5/VRN_5	R4	DCI
5	IO_L27N_5/VREF_5	R5	VREF
5	IO_L27P_5	P5	I/O
5	IO_L28N_5/D6	N6	DUAL
5	IO_L28P_5/D7	M6	DUAL
5	IO_L29N_5	R6	I/O
5	IO_L29P_5/VREF_5	P6	VREF
5	IO_L30N_5	N7	I/O
5	IO_L30P_5	M7	I/O
5	IO_L31N_5/D4	T7	DUAL
5	IO_L31P_5/D5	R7	DUAL
5	IO_L32N_5/GCLK3	P8	GCLK
5	IO_L32P_5/GCLK2	N8	GCLK
5	VCCO_5	L7	VCCO
5	VCCO_5	L8	VCCO
5	VCCO_5	M8	VCCO
6	IO	K1	I/O
6	IO_L01N_6/VRP_6	R1	DCI
6	IO_L01P_6/VRN_6	P1	DCI
6	IO_L16N_6	P2	I/O

Table 100: **FG456 Package Pinout *(Cont'd)***

Bank	3S400 Pin Name	3S1000, 3S1500, 3S2000 Pin Name	FG456 Pin Number	Type
4	IO_L30N_4/D2	IO_L30N_4/D2	U12	DUAL
4	IO_L30P_4/D3	IO_L30P_4/D3	V12	DUAL
4	IO_L31N_4/INIT_B	IO_L31N_4/INIT_B	W12	DUAL
4	IO_L31P_4/DOUT/BUSY	IO_L31P_4/DOUT/BUSY	Y12	DUAL
4	IO_L32N_4/GCLK1	IO_L32N_4/GCLK1	AA12	GCLK
4	IO_L32P_4/GCLK0	IO_L32P_4/GCLK0	AB12	GCLK
4	VCCO_4	VCCO_4	T12	VCCO
4	VCCO_4	VCCO_4	T13	VCCO
4	VCCO_4	VCCO_4	T14	VCCO
4	VCCO_4	VCCO_4	U15	VCCO
4	VCCO_4	VCCO_4	Y15	VCCO
5	IO	IO	U7	I/O
5	N.C. (◆)	IO	U9	I/O
5	IO	IO	U10	I/O
5	IO	IO	U11	I/O
5	IO	IO	V7	I/O
5	IO	IO	V10	I/O
5	IO/VREF_5	IO/VREF_5	AB11	VREF
5	IO/VREF_5	IO/VREF_5	U6	VREF
5	IO_L01N_5/RDWR_B	IO_L01N_5/RDWR_B	Y4	DUAL
5	IO_L01P_5/CS_B	IO_L01P_5/CS_B	AA3	DUAL
5	IO_L06N_5	IO_L06N_5	AB4	I/O
5	IO_L06P_5	IO_L06P_5	AA4	I/O
5	IO_L09N_5	IO_L09N_5	Y5	I/O
5	IO_L09P_5	IO_L09P_5	W5	I/O
5	IO_L10N_5/VRP_5	IO_L10N_5/VRP_5	AB5	DCI
5	IO_L10P_5/VRN_5	IO_L10P_5/VRN_5	AA5	DCI
5	IO_L15N_5	IO_L15N_5	W6	I/O
5	IO_L15P_5	IO_L15P_5	V6	I/O
5	IO_L16N_5	IO_L16N_5	AA6	I/O
5	IO_L16P_5	IO_L16P_5	Y6	I/O
5	N.C. (◆)	IO_L19N_5	Y7	I/O
5	N.C. (◆)	IO_L19P_5/ VREF_5	W7	VREF
5	N.C. (◆)	IO_L22N_5	AB7	I/O
5	N.C. (◆)	IO_L22P_5	AA7	I/O
5	IO_L24N_5	IO_L24N_5	W8	I/O
5	IO_L24P_5	IO_L24P_5	V8	I/O
5	IO_L25N_5	IO_L25N_5	AB8	I/O
5	IO_L25P_5	IO_L25P_5	AA8	I/O

Table 100: **FG456 Package Pinout *(Cont'd)***

Bank	3S400 Pin Name	3S1000, 3S1500, 3S2000 Pin Name	FG456 Pin Number	Type
5	IO_L27N_5/VREF_5	IO_L27N_5/VREF_5	W9	VREF
5	IO_L27P_5	IO_L27P_5	V9	I/O
5	IO_L28N_5/D6	IO_L28N_5/D6	AB9	DUAL
5	IO_L28P_5/D7	IO_L28P_5/D7	AA9	DUAL
5	IO_L29N_5	IO_L29N_5	Y10	I/O
5	IO_L29P_5/VREF_5	IO_L29P_5/VREF_5	W10	VREF
5	IO_L30N_5	IO_L30N_5	AB10	I/O
5	IO_L30P_5	IO_L30P_5	AA10	I/O
5	IO_L31N_5/D4	IO_L31N_5/D4	W11	DUAL
5	IO_L31P_5/D5	IO_L31P_5/D5	V11	DUAL
5	IO_L32N_5/GCLK3	IO_L32N_5/GCLK3	AA11	GCLK
5	IO_L32P_5/GCLK2	IO_L32P_5/GCLK2	Y11	GCLK
5	VCCO_5	VCCO_5	T9	VCCO
5	VCCO_5	VCCO_5	T10	VCCO
5	VCCO_5	VCCO_5	T11	VCCO
5	VCCO_5	VCCO_5	U8	VCCO
5	VCCO_5	VCCO_5	Y8	VCCO
6	IO	IO	Y1	I/O
6	IO_L01N_6/VRP_6	IO_L01N_6/VRP_6	Y3	DCI
6	IO_L01P_6/VRN_6	IO_L01P_6/VRN_6	Y2	DCI
6	IO_L16N_6	IO_L16N_6	W4	I/O
6	IO_L16P_6	IO_L16P_6	W3	I/O
6	IO_L17N_6	IO_L17N_6	W2	I/O
6	IO_L17P_6/VREF_6	IO_L17P_6/VREF_6	W1	VREF
6	IO_L19N_6	IO_L19N_6	V5	I/O
6	IO_L19P_6	IO_L19P_6	U5	I/O
6	IO_L20N_6	IO_L20N_6	V4	I/O
6	IO_L20P_6	IO_L20P_6	V3	I/O
6	IO_L21N_6	IO_L21N_6	V2	I/O
6	IO_L21P_6	IO_L21P_6	V1	I/O
6	IO_L22N_6	IO_L22N_6	T6	I/O
6	IO_L22P_6	IO_L22P_6	T5	I/O
6	IO_L23N_6	IO_L23N_6	U4	I/O
6	IO_L23P_6	IO_L23P_6	T4	I/O
6	IO_L24N_6/VREF_6	IO_L24N_6/VREF_6	U3	VREF
6	IO_L24P_6	IO_L24P_6	U2	I/O
6	N.C. (◆)	IO_L26N_6	T3	I/O
6	N.C. (◆)	IO_L26P_6	R4	I/O
6	IO_L27N_6	IO_L27N_6	T2	I/O
6	IO_L27P_6	IO_L27P_6	T1	I/O

Table 100: **FG456 Package Pinout *(Cont'd)***

Bank	3S400 Pin Name	3S1000, 3S1500, 3S2000 Pin Name	FG456 Pin Number	Type
N/A	GND	GND	B21	GND
N/A	GND	GND	C9	GND
N/A	GND	GND	C14	GND
N/A	GND	GND	J3	GND
N/A	GND	GND	J9	GND
N/A	GND	GND	J10	GND
N/A	GND	GND	J11	GND
N/A	GND	GND	J12	GND
N/A	GND	GND	J13	GND
N/A	GND	GND	J14	GND
N/A	GND	GND	J20	GND
N/A	GND	GND	K9	GND
N/A	GND	GND	K10	GND
N/A	GND	GND	K11	GND
N/A	GND	GND	K12	GND
N/A	GND	GND	K13	GND
N/A	GND	GND	K14	GND
N/A	GND	GND	L9	GND
N/A	GND	GND	L10	GND
N/A	GND	GND	L11	GND
N/A	GND	GND	L12	GND
N/A	GND	GND	L13	GND
N/A	GND	GND	L14	GND
N/A	GND	GND	M9	GND
N/A	GND	GND	M10	GND
N/A	GND	GND	M11	GND
N/A	GND	GND	M12	GND
N/A	GND	GND	M13	GND
N/A	GND	GND	M14	GND
N/A	GND	GND	N9	GND
N/A	GND	GND	N10	GND
N/A	GND	GND	N11	GND
N/A	GND	GND	N12	GND
N/A	GND	GND	N13	GND
N/A	GND	GND	N14	GND
N/A	GND	GND	P3	GND
N/A	GND	GND	P9	GND
N/A	GND	GND	P10	GND
N/A	GND	GND	P11	GND
N/A	GND	GND	P12	GND

Table 103: **FG676 Package Pinout *(Cont'd)***

Bank	XC3S1000 Pin Name	XC3S1500 Pin Name	XC3S2000 Pin Name	XC3S4000 Pin Name	XC3S5000 Pin Name	FG676 Pin Number	Type
4	IO_L22N_4/VREF_4	IO_L22N_4/VREF_4	IO_L22N_4/VREF_4	IO_L22N_4/VREF_4	IO_L22N_4/VREF_4	AD17	VREF
4	IO_L22P_4	IO_L22P_4	IO_L22P_4	IO_L22P_4	IO_L22P_4	AB17	I/O
4	N.C. (◆)	IO_L23N_4	IO_L23N_4	IO_L23N_4	IO_L23N_4	AE17	I/O
4	N.C. (◆)	IO_L23P_4	IO_L23P_4	IO_L23P_4	IO_L23P_4	AF17	I/O
4	IO_L24N_4	IO_L24N_4	IO_L24N_4	IO_L24N_4	IO_L24N_4	Y16	I/O
4	IO_L24P_4	IO_L24P_4	IO_L24P_4	IO_L24P_4	IO_L24P_4	AA16	I/O
4	IO_L25N_4	IO_L25N_4	IO_L25N_4	IO_L25N_4	IO_L25N_4	AB16	I/O
4	IO_L25P_4	IO_L25P_4	IO_L25P_4	IO_L25P_4	IO_L25P_4	AC16	I/O
4	N.C. (◆)	IO_L26N_4	IO_L26N_4	IO_L26N_4	IO_L26N_4	AE16	I/O
4	N.C. (◆)	IO_L26P_4/VREF_4	IO_L26P_4/VREF_4	IO_L26P_4/VREF_4	IO_L26P_4/VREF_4	AF16	VREF
4	IO_L27N_4/DIN/D0	IO_L27N_4/DIN/D0	IO_L27N_4/DIN/D0	IO_L27N_4/DIN/D0	IO_L27N_4/DIN/D0	Y15	DUAL
4	IO_L27P_4/D1	IO_L27P_4/D1	IO_L27P_4/D1	IO_L27P_4/D1	IO_L27P_4/D1	W14	DUAL
4	IO_L28N_4	IO_L28N_4	IO_L28N_4	IO_L28N_4	IO_L28N_4	AA15	I/O
4	IO_L28P_4	IO_L28P_4	IO_L28P_4	IO_L28P_4	IO_L28P_4	AB15	I/O
4	IO_L29N_4	IO_L29N_4	IO_L29N_4	IO_L29N_4	IO_L29N_4	AE15	I/O
4	IO_L29P_4	IO_L29P_4	IO_L29P_4	IO_L29P_4	IO_L29P_4	AF15	I/O
4	IO_L30N_4/D2	IO_L30N_4/D2	IO_L30N_4/D2	IO_L30N_4/D2	IO_L30N_4/D2	Y14	DUAL
4	IO_L30P_4/D3	IO_L30P_4/D3	IO_L30P_4/D3	IO_L30P_4/D3	IO_L30P_4/D3	AA14	DUAL
4	IO_L31N_4/INIT_B	IO_L31N_4/INIT_B	IO_L31N_4/INIT_B	IO_L31N_4/INIT_B	IO_L31N_4/INIT_B	AC14	DUAL
4	IO_L31P_4/ DOUT/BUSY	IO_L31P_4/ DOUT/BUSY	IO_L31P_4/ DOUT/BUSY	IO_L31P_4/ DOUT/BUSY	IO_L31P_4/ DOUT/BUSY	AD14	DUAL
4	IO_L32N_4/GCLK1	IO_L32N_4/GCLK1	IO_L32N_4/GCLK1	IO_L32N_4/GCLK1	IO_L32N_4/GCLK1	AE14	GCLK
4	IO_L32P_4/GCLK0	IO_L32P_4/GCLK0	IO_L32P_4/GCLK0	IO_L32P_4/GCLK0	IO_L32P_4/GCLK0	AF14	GCLK
4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	AD16	VCCO
4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	AD20	VCCO
4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	U14	VCCO
4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	V14	VCCO
4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	V15	VCCO
4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	V16	VCCO
4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	W17	VCCO
4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	VCCO_4	W18	VCCO
5	IO	IO	IO	IO	IO	AA7	I/O
5	IO	IO	IO	IO	IO	AA13	I/O
5	IO	IO	IO	IO	IO_L17P_5[3]	AB9	I/O
5	N.C. (◆)	IO	IO	IO	IO_L17N_5[3]	AC9	I/O
5	IO	IO	IO	IO	IO	AC11	I/O
5	IO	IO	IO	IO	IO	AD10	I/O
5	IO	IO	IO	IO	IO	AD12	I/O
5	IO	IO	IO	IO	IO	AF4	I/O
5	IO	IO	IO	IO	IO	Y8	I/O
5	IO/VREF_5	IO/VREF_5	IO/VREF_5	IO/VREF_5	IO/VREF_5	AF5	VREF
5	IO/VREF_5	IO/VREF_5	IO/VREF_5	IO/VREF_5	IO/VREF_5	AF13	VREF
5	IO_L01N_5/RDWR_B	IO_L01N_5/RDWR_B	IO_L01N_5/RDWR_B	IO_L01N_5/RDWR_B	IO_L01N_5/RDWR_B	AC5	DUAL

Table 110: **FG1156 Package Pinout *(Cont'd)***

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
0	IO_L03P_0	IO_L03P_0	B5	I/O
0	IO_L04N_0	IO_L04N_0	D6	I/O
0	IO_L04P_0	IO_L04P_0	C6	I/O
0	IO_L05N_0	IO_L05N_0	B6	I/O
0	IO_L05P_0/VREF_0	IO_L05P_0/VREF_0	A6	VREF
0	IO_L06N_0	IO_L06N_0	F7	I/O
0	IO_L06P_0	IO_L06P_0	E7	I/O
0	IO_L07N_0	IO_L07N_0	G9	I/O
0	IO_L07P_0	IO_L07P_0	F9	I/O
0	IO_L08N_0	IO_L08N_0	D9	I/O
0	IO_L08P_0	IO_L08P_0	C9	I/O
0	IO_L09N_0	IO_L09N_0	J10	I/O
0	IO_L09P_0	IO_L09P_0	H10	I/O
0	IO_L10N_0	IO_L10N_0	G10	I/O
0	IO_L10P_0	IO_L10P_0	F10	I/O
0	IO_L11N_0	IO_L11N_0	L12	I/O
0	IO_L11P_0	IO_L11P_0	K12	I/O
0	IO_L12N_0	IO_L12N_0	J12	I/O
0	IO_L12P_0	IO_L12P_0	H12	I/O
0	IO_L13N_0	IO_L13N_0	F12	I/O
0	IO_L13P_0	IO_L13P_0	E12	I/O
0	IO_L14N_0	IO_L14N_0	D12	I/O
0	IO_L14P_0	IO_L14P_0	C12	I/O
0	IO_L15N_0	IO_L15N_0	B12	I/O
0	IO_L15P_0	IO_L15P_0	A12	I/O
0	IO_L16N_0	IO_L16N_0	H13	I/O
0	IO_L16P_0	IO_L16P_0	G13	I/O
0	IO_L17N_0	IO_L17N_0	D13	I/O
0	IO_L17P_0	IO_L17P_0	C13	I/O
0	IO_L18N_0	IO_L18N_0	L14	I/O
0	IO_L18P_0	IO_L18P_0	K14	I/O
0	IO_L19N_0	IO_L19N_0	H14	I/O
0	IO_L19P_0	IO_L19P_0	G14	I/O
0	IO_L20N_0	IO_L20N_0	F14	I/O
0	IO_L20P_0	IO_L20P_0	E14	I/O
0	IO_L21N_0	IO_L21N_0	D14	I/O
0	IO_L21P_0	IO_L21P_0	C14	I/O
0	IO_L22N_0	IO_L22N_0	B14	I/O
0	IO_L22P_0	IO_L22P_0	A14	I/O
0	IO_L23N_0	IO_L23N_0	K15	I/O

Table 110: **FG1156 Package Pinout *(Cont'd)***

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
N/A	GND	GND	AA18	GND
N/A	GND	GND	AA19	GND
N/A	GND	GND	AA20	GND
N/A	GND	GND	AA21	GND
N/A	GND	GND	AB1	GND
N/A	GND	GND	AB17	GND
N/A	GND	GND	AB18	GND
N/A	GND	GND	AB26	GND
N/A	GND	GND	AB30	GND
N/A	GND	GND	AB34	GND
N/A	GND	GND	AB5	GND
N/A	GND	GND	AB9	GND
N/A	GND	GND	AD3	GND
N/A	GND	GND	AD32	GND
N/A	GND	GND	AE10	GND
N/A	GND	GND	AE25	GND
N/A	GND	GND	AF1	GND
N/A	GND	GND	AF13	GND
N/A	GND	GND	AF16	GND
N/A	GND	GND	AF19	GND
N/A	GND	GND	AF22	GND
N/A	GND	GND	AF30	GND
N/A	GND	GND	AF34	GND
N/A	GND	GND	AF5	GND
N/A	GND	GND	AH28	GND
N/A	GND	GND	AH7	GND
N/A	GND	GND	AK1	GND
N/A	GND	GND	AK13	GND
N/A	GND	GND	AK16	GND
N/A	GND	GND	AK19	GND
N/A	GND	GND	AK22	GND
N/A	GND	GND	AK26	GND
N/A	GND	GND	AK30	GND
N/A	GND	GND	AK34	GND
N/A	GND	GND	AK5	GND
N/A	GND	GND	AK9	GND
N/A	GND	GND	AM11	GND
N/A	GND	GND	AM24	GND
N/A	GND	GND	AM3	GND
N/A	GND	GND	AM32	GND

Table 110: **FG1156 Package Pinout *(Cont'd)***

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
N/A	GND	GND	J22	GND
N/A	GND	GND	J30	GND
N/A	GND	GND	J34	GND
N/A	GND	GND	J5	GND
N/A	GND	GND	K10	GND
N/A	GND	GND	K25	GND
N/A	GND	GND	L3	GND
N/A	GND	GND	L32	GND
N/A	GND	GND	N1	GND
N/A	GND	GND	N17	GND
N/A	GND	GND	N18	GND
N/A	GND	GND	N26	GND
N/A	GND	GND	N30	GND
N/A	GND	GND	N34	GND
N/A	GND	GND	N5	GND
N/A	GND	GND	N9	GND
N/A	GND	GND	P14	GND
N/A	GND	GND	P15	GND
N/A	GND	GND	P16	GND
N/A	GND	GND	P17	GND
N/A	GND	GND	P18	GND
N/A	GND	GND	P19	GND
N/A	GND	GND	P20	GND
N/A	GND	GND	P21	GND
N/A	GND	GND	R14	GND
N/A	GND	GND	R15	GND
N/A	GND	GND	R16	GND
N/A	GND	GND	R17	GND
N/A	GND	GND	R18	GND
N/A	GND	GND	R19	GND
N/A	GND	GND	R20	GND
N/A	GND	GND	R21	GND
N/A	GND	GND	T1	GND
N/A	GND	GND	T14	GND
N/A	GND	GND	T15	GND
N/A	GND	GND	T16	GND
N/A	GND	GND	T17	GND
N/A	GND	GND	T18	GND
N/A	GND	GND	T19	GND
N/A	GND	GND	T20	GND

User I/Os by Bank

Note: The FG(G)1156 package is discontinued. See http://www.xilinx.com/support/documentation/spartan-3_customer_notices.htm.

Table 111 indicates how the available user-I/O pins are distributed between the eight I/O banks for the XC3S4000 in the FG1156 package. Similarly, Table 112 shows how the available user-I/O pins are distributed between the eight I/O banks for the XC3S5000 in the FG1156 package.

Table 111: **User I/Os Per Bank for XC3S4000 in FG1156 Package**

Package Edge	I/O Bank	Maximum I/O	All Possible I/O Pins by Type				
			I/O	DUAL	DCI	VREF	GCLK
Top	0	90	79	0	2	7	2
	1	90	79	0	2	7	2
Right	2	88	80	0	2	6	0
	3	88	79	0	2	7	0
Bottom	4	90	73	6	2	7	2
	5	90	73	6	2	7	2
Left	6	88	79	0	2	7	0
	7	88	79	0	2	7	0

Notes:

1. The FG1156 and FGG1156 packages are discontinued. See www.xilinx.com/support/documentation/spartan-3.htm#19600.

Table 112: **User I/Os Per Bank for XC3S5000 in FG1156 Package**

Package Edge	I/O Bank	Maximum I/O	All Possible I/O Pins by Type				
			I/O	DUAL	DCI	VREF	GCLK
Top	0	100	89	0	2	7	2
	1	100	89	0	2	7	2
Right	2	96	87	0	2	7	0
	3	96	87	0	2	7	0
Bottom	4	100	83	6	2	7	2
	5	100	83	6	2	7	2
Left	6	96	87	0	2	7	0
	7	96	87	0	2	7	0

Notes:

1. The FG1156 and FGG1156 packages are discontinued. See www.xilinx.com/support/documentation/spartan-3.htm#19600.

Revision History

Date	Version	Description
04/03/03	1.0	Initial Xilinx release.
04/21/03	1.1	Added information on the VQ100 package footprint, including a complete pinout table (Table 87) and footprint diagram (Figure 44). Updated Table 85 with final I/O counts for the VQ100 package. Also added final differential I/O pair counts for the TQ144 package. Added clarifying comments to HSWAP_EN pin description on page 119. Updated the footprint diagram for the FG900 package shown in Figure 55a and Figure 55b. Some thick lines separating I/O banks were incorrect. Made cosmetic changes to Figure 40, Figure 42, and Figure 43. Updated Xilinx hypertext links. Added XC3S200 and XC3S400 to Pin Name column in Table 91.
05/12/03	1.1.1	AM32 pin was missing GND label in FG1156 package diagram (Figure 53).
07/11/03	1.1.2	Corrected misspellings of GCLK in Table 69 and Table 70. Changed CMOS25 to LVCMOS25 in Dual-Purpose Pin I/O Standard During Configuration section. Clarified references to Module 2. For XC3S5000 in FG1156 package, corrected N.C. symbol to a black square in Table 110, key, and package drawing.
07/29/03	1.2	Corrected pin names on FG1156 package. Some package balls incorrectly included LVDS pair names. The affected balls on the FG1156 package include G1, G2, G33, G34, U9, U10, U25, U26, V9, V10, V25, V26, AH1, AH2, AH33, AH34. The number of LVDS pairs is unaffected. Modified affected balls and re-sorted rows in Table 110. Updated affected balls in Figure 53. Also updated ASCII and Excel electronic versions of FG1156 pinout.
08/19/03	1.2.1	Removed 100 MHz ConfigRate option in CCLK: Configuration Clock section and in Table 80. Added note that TDO is a totem-pole output in Table 77.
10/09/03	1.2.2	Some pins had incorrect bank designations and were improperly sorted in Table 93. No pin names or functions changed. Renamed DCI_IN to DCI and added black diamond to N.C. pins in Table 93. In Figure 47, removed some extraneous text from pin 106 and corrected spelling of pins 45, 48, and 81.
12/17/03	1.3	Added FG320 pin tables and pinout diagram (FG320: 320-lead Fine-pitch Ball Grid Array). Made cosmetic changes to the TQ144 footprint (Figure 46), the PQ208 footprint (Figure 47), the FG676 footprint (Figure 53), and the FG900 footprint (Figure 55). Clarified wording in Precautions When Using the JTAG Port in 3.3V Environments section.
02/27/04	1.4	Clarified wording in Using JTAG Port After Configuration section. In Table 81, reduced package height for FG320 and increased maximum I/O values for the FG676, FG900, and FG1156 packages.
07/13/04	1.5	Added information on lead-free (Pb-free) package options to the Package Overview section plus Table 81 and Table 83. Clarified the VRN_# reference resistor requirements for I/O standards that use single termination as described in the DCI Termination Types section and in Figure 42b. Graduated from Advance Product Specification to Product Specification.
08/24/04	1.5.1	Removed XC3S2000 references from FG1156: 1156-lead Fine-pitch Ball Grid Array.
01/17/05	1.6	Added XC3S50 in CP132 package option. Added XC3S2000 in FG456 package option. Added XC3S4000 in FG676 package option. Added Selecting the Right Package Option section. Modified or added Table 81, Table 83, Table 84, Table 85, Table 89, Table 90, Table 100, Table 102, Table 103, Table 106, Figure 45, and Figure 53.
08/19/05	1.7	Removed term “weak” from the description of pull-up and pull-down resistors. Added IDCODE Register values. Added signal integrity precautions to CCLK: Configuration Clock and indicated that CCLK should be treated as an I/O during Master mode in Table 79.
04/03/06	2.0	Added Package Thermal Characteristics. Updated Figure 41 to make it a more obvious example. Added detail about which pins have dedicated pull-up resistors during configuration, regardless of the HSWAP_EN value to Table 70 and to Pin Behavior During Configuration. Updated Precautions When Using the JTAG Port in 3.3V Environments.
04/26/06	2.1	Corrected swapped data row in Table 86. The Theta-JA with zero airflow column was swapped with the Theta-JC column. Made additional notations on CONFIG and JTAG pins that have pull-up resistors during configuration, regardless of the HSWAP_EN input.
05/25/07	2.2	Added link on page 128 to Material Declaration Data Sheets. Corrected units typo in Table 74. Added Note 1 to Table 103 about VREF for XC3S1500 in FG676.